

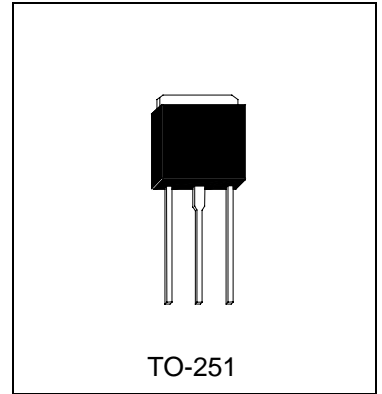


HI10387

NPN EPITAXIAL PLANAR TRANSISTOR

Description

The HI10387 is designed for general-purpose amplifier and low-speed switching applications.



Absolute Maximum Ratings (Ta=25°C)

- Maximum Temperatures
Storage Temperature -55~+150 °C
Junction Temperature 150°C Maximum
- Maximum Power Dissipation
Total Power Dissipation (Tc=25°C) 65 W
Total Power Dissipation (Ta=25°C) 2 W
- Maximum Voltages and Currents (Ta=25°C)
VCBO Collector to Base Voltage 80 V
VCEO Collector to Emitter Voltage 80 V
VEBO Emitter to Base Voltage 5 V
IC Collector Current 10 A

Characteristics (Ta=25°C)

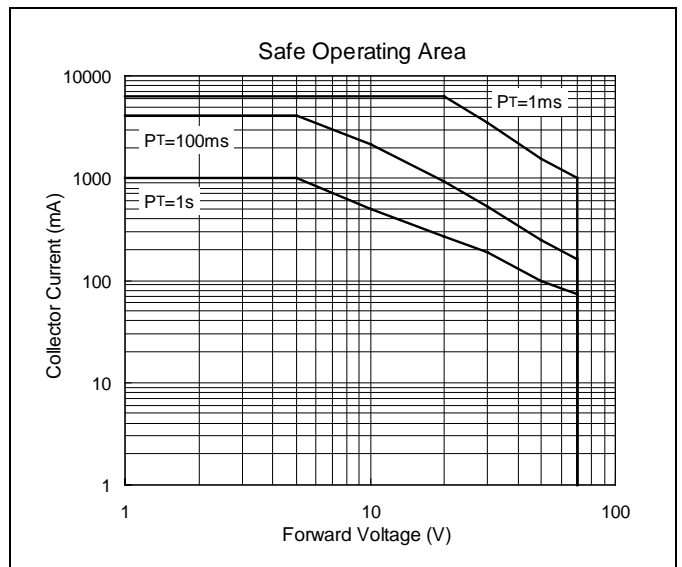
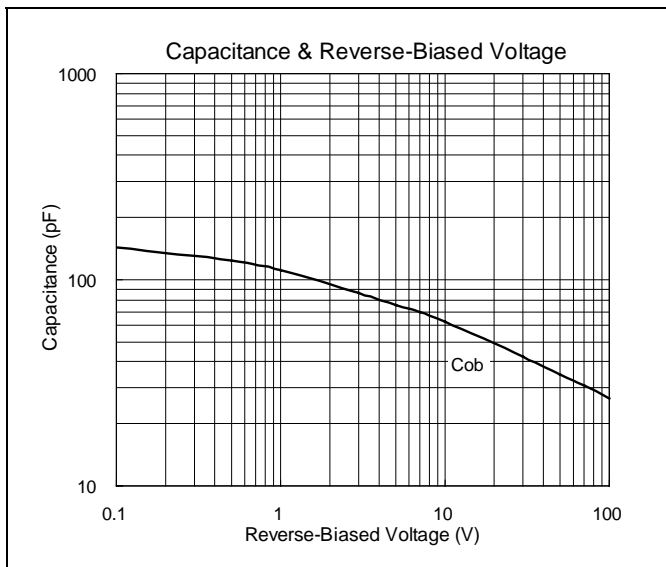
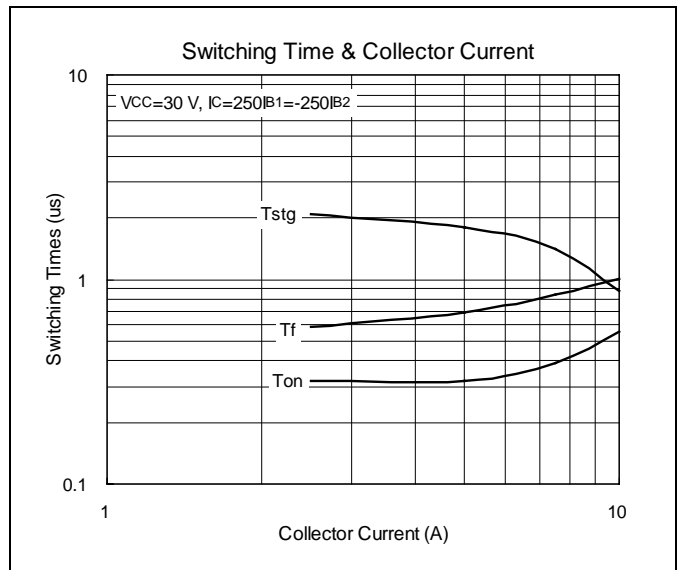
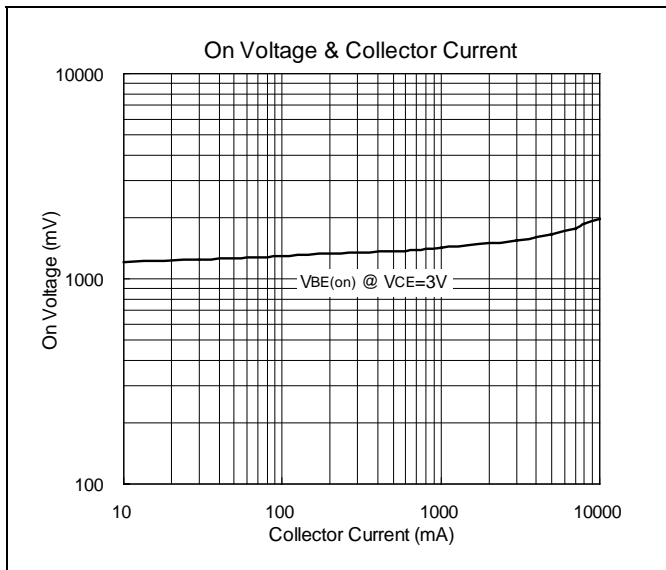
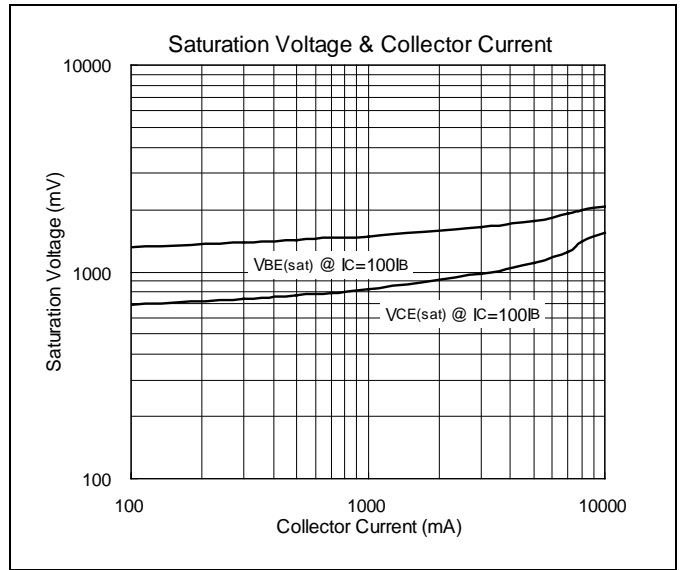
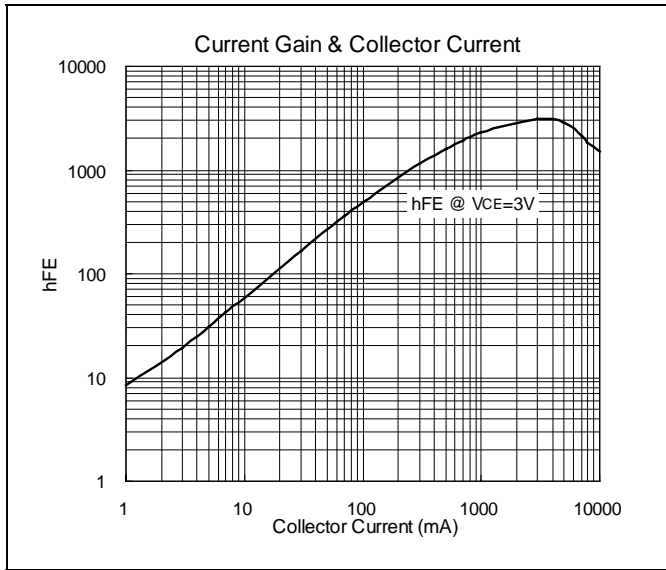
Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BVCEO	80	-	-	V	IC=200mA
ICBO	-	-	100	uA	VCB=160V
IEBO	-	-	2	mA	VEB=5V
ICEO	-	-	1	mA	VCE=80V
ICEV	-	-	300	uA	VCE=80V, VBE(Off)=1.5V
VCE(sat)1	-	-	2	V	IC=5A, IB=10mA
VCE(sat)2	-	-	3	V	IC=10A, IB=100mA
VCE(sat)3	-	-	1.5	V	IC=5A, IB=2.5mA
VBE(sat)	-	-	2	V	IC=5A, IB=5mA
VBE(on)1	-	-	2.8	V	VCE=3V, IC=5A
VBE(on)2	-	-	4.5	V	VCE=3V, IC=10A
VFEC	-	-	3	V	IC=5A
hFE1	2	-	20	K	IC=5A, VCE=3V
hFE2	100	-	-		VCE=3V, IC=10A

Classification Of VCE(sat)1

Rank	KA	KB	KC	NORMAL
VCE(sat)1	<1.5, BVCEO>130V	<1.1V	<1.3V	<2V

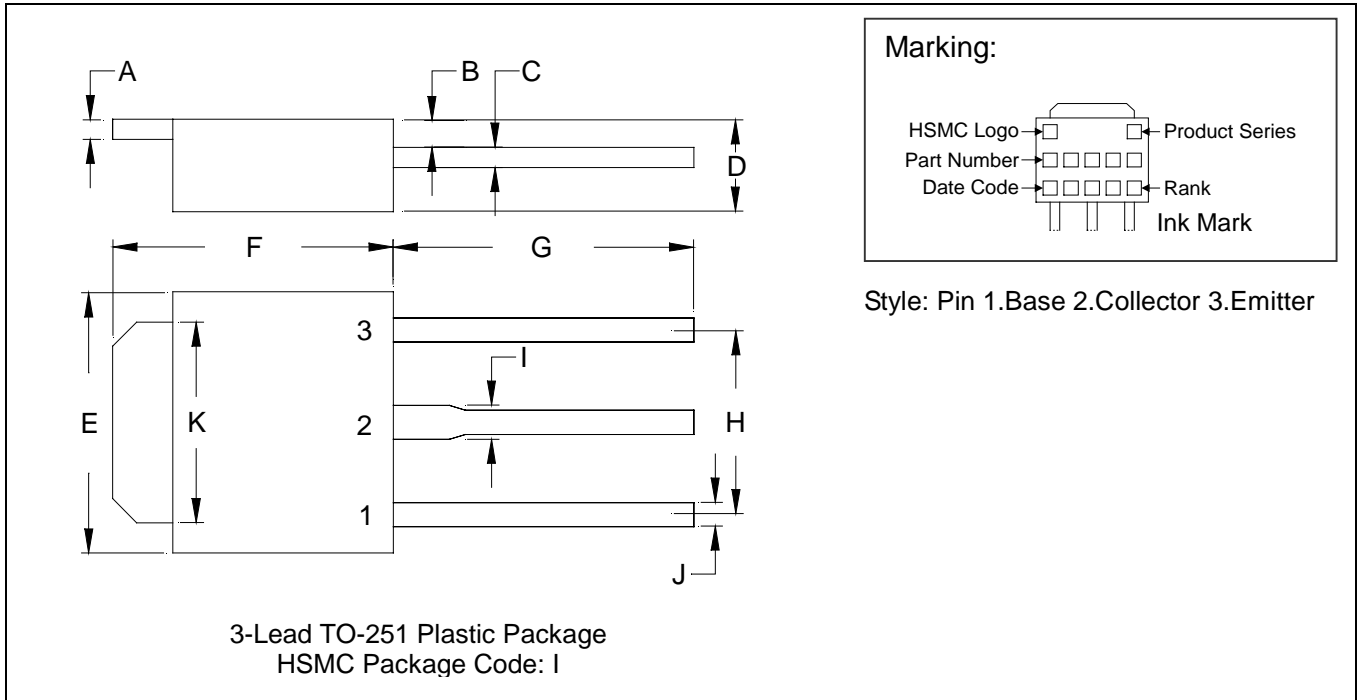


Characteristics Curve





TO-251 Dimension



*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.0177	0.0217	0.45	0.55	G	0.2559	-	6.50	-
B	0.0354	0.0591	0.90	1.50	H	-	*0.1811	-	*4.60
C	0.0177	0.0236	0.45	0.60	I	-	0.0354	-	0.90
D	0.0866	0.0945	2.20	2.40	J	-	0.0315	-	0.80
E	0.2520	0.2677	6.40	6.80	K	0.2047	0.2165	5.20	5.50
F	0.2677	0.2835	6.80	7.20					

- Notes:**
- 1.Dimension and tolerance based on our Spec. dated May. 24,1995.
 - 2.Controlling dimension: millimeters.
 - 3.Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 - 4.If there is any question with packing specification or packing method, please contact your local HSMC sales office.

Material:

- Lead: 42 Alloy ; solder plating
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0

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